

TS971, TS972, TS974

Output rail-to-rail very low noise operational amplifier

Features

- Rail-to-rail output voltage swing ±2.4 V at V_{CC} = ±2.5 V
- Very low noise level: 4 nV/√Hz
- Ultra low distortion: 0.003%
- High dynamic features: 12 MHz, 4 V/µs
- Operating range: 2.7 to 10 V
- ESD protection (2 kV)
- Latch-up immunity (class A)

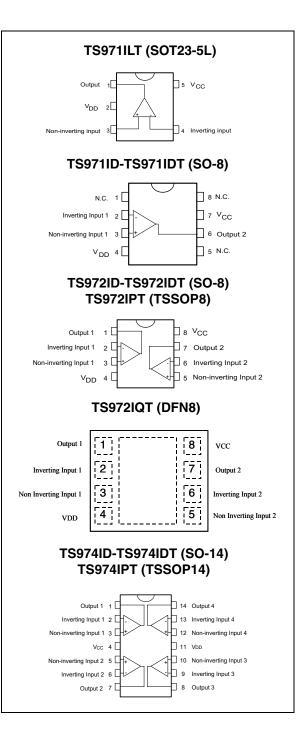
Applications

- Portable devices (CD players, PDAs)
- Portable communication (cell phones, pagers)
- Instrumentation and sensoring
- Professional audio circuits

Description

The TS97x family of operational amplifiers operates with voltages as low as ± 1.35 V and features output rail-to-rail signal swing. The TS97x are particularly well suited for portable and battery-supplied equipment. Very low noise and low distortion characteristics make them ideal for audio pre-amplification.

The TS971 is available in a variety of packages to suit all types of applications. For applications where space-saving is critical, the SOT23 package ($2.8 \times 2.9 \text{ mm}$) or the DFN package ($3 \times 3 \text{ mm}$) simplify the board design because they can be placed everywhere.



May 2010

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Absolute maximun	n ratings and	l operating	conditions
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Symbol	Parameter	Value	Unit
V _{CC}	Supply voltage ⁽¹⁾	12	V
V _{id}	Differential input voltage (2)	±1	V
V _{in}	Input voltage ⁽³⁾	V_{DD} -0.3 to V_{CC} +0.3	V
T _{stg}	Storage temperature range	-65 to +150	
Тj	Maximum junction temperature	150	°C
R _{thja}	Thermal resistance junction to ambient ⁽⁴⁾ SOT23-5 DFN8 SO-8 SO-14 TSSOP8 TSSOP14	250 40 125 105 120 100	°C/W
R _{thjc}	Thermal resistance junction to case ⁽⁴⁾ SOT23-5 DFN8 SO-8 SO-14 TSSOP8 TSSOP14	81 5.2 40 31 37 32	°C/W
	HBM: human body model ⁽⁵⁾	2	kV
ESD	MM: machine model ⁽⁶⁾	200	V
	CDM: charged device model ⁽⁷⁾	1.5	kV
	Lead temperature (soldering, 10sec)	260	°C

	Table 1.	Absolute	maximum	ratings	AMR
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1. All voltage values, except differential voltage are with respect to network ground terminal.

2. Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.

3. The magnitude of input and output voltages must never exceed V_CC +0.3 V.

4. Short-circuits can cause excessive heating and destructive dissipation. Values are typical.

 Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5kΩ resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.

6. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are floating.

7. Charged device model: all pins and package are charged together to the specified voltage and then discharged directly to ground through only one pin. This is done for all pins.

No value specified for CDM on SOT23-5 package.



Symbol	Parameter	Value	Unit
V _{CC}	Supply voltage	2.7 to 10	V
V _{icm}	Common mode input voltage range	V _{DD} +1.15 to V _{CC} -1.15	V
T _{oper}	Operating free air temperature range	-40 to +125	°C

Table 2. Operating conditions

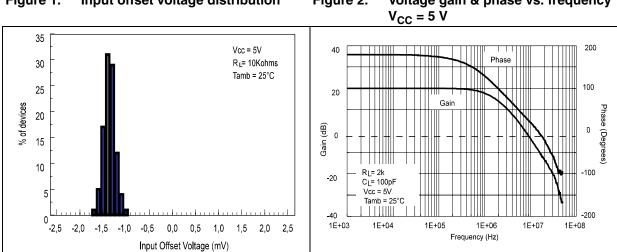


2 Electrical characteristics

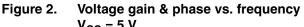
Table 3.	$v_{CC} = +2.5 v$, $v_{DD} = -2.5 v$, $I_{amb} = 25 °C$ (unless otherwise specified)							
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
V _{io}	Input offset voltage	T _{min} ≤T _{amb} ≤T _{max}		1	5 7	mV		
DVio	Input offset voltage drift	$V_{icm} = 0 V, V_o = 0 V$		5		µV/°C		
I _{io}	Input offset current	$V_{icm} = 0 V, V_o = 0 V$		10	150	nA		
I _{ib}	Input bias current	$V_{icm} = 0 V, V_o = 0 V$ $T_{min} \le T_{amb} \le T_{max}$		200 200	750 1000	nA		
V _{icm}	Common mode input voltage range		-1.35		1.35	V		
CMR	Common mode rejection ratio	$V_{icm} = \pm 1.35 V$	60	85		dB		
SVR	Supply voltage rejection ratio	$V_{CC} = \pm 2 V \text{ to } \pm 3 V$	60	70		dB		
A _{vd}	Large signal voltage gain	$R_L = 2 \ k\Omega$	70	80		dB		
V _{OH}	High level output voltage	$R_L = 2 \ k\Omega$	2	2.4		V		
V _{OL}	Low level output voltage	$R_L = 2 k\Omega$		-2.4	-2	V		
I _{source}	Output source current			1.5		mA		
I _{sink}	Output sink current			100		mA		
I _{CC}	Supply current per amplifier	Unity gain - no load		2	2.8	mA		
GBP	Gain bandwidth product	$f = 100 \text{ kHz}, \text{ R}_{L} = 2 \text{ k}\Omega, \text{ C}_{L} = 100 \text{ pF}$	8.5	12		MHz		
SR	Slew rate	$A_{V} = 1, V_{in} = \pm 1 V$	2.8	4		V/µs		
Øm	Phase margin at unit gain	$R_{L} = 2 k\Omega, C_{L} = 100 pF$		60		Degrees		
Gm	Gain margin	$R_{L} = 2 k\Omega, C_{L} = 100 pF$		10		dB		
e _n	Equivalent input noise voltage	f = 100 kHz		4		nV/√Hz		
THD	Total harmonic distortion	f = 1 kHz, A_V = -1, R_L = 10 kΩ		0.003		%		

Table 3. $V_{CC} = +2.5 \text{ V}, V_{DD} = -2.5 \text{ V}, T_{amb} = 25^{\circ}\text{C}$ (unless otherwise specified)

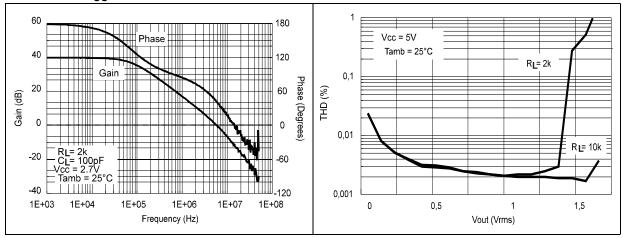


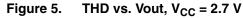


Input offset voltage distribution Figure 1.

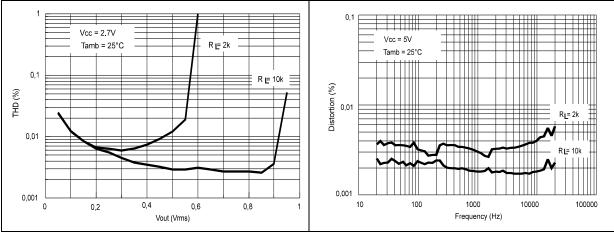


THS vs. V_{out} , V_{CC} = 5 V Figure 3. Voltage gain & phase vs. frequency Figure 4. $V_{CC} = 2.7 V$

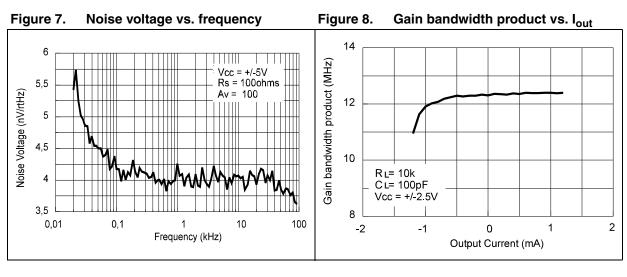














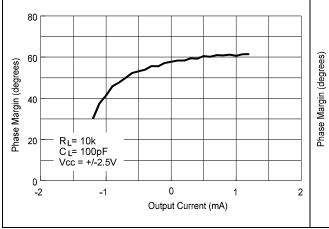
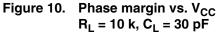
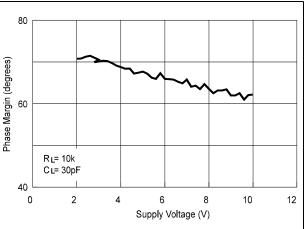
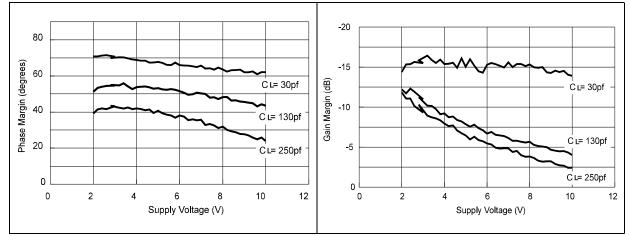


Figure 11. Phase margin vs. V_{CC} $C_L = 30, 130$ and 250 pF









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3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



3.1 SOT23-5 package information



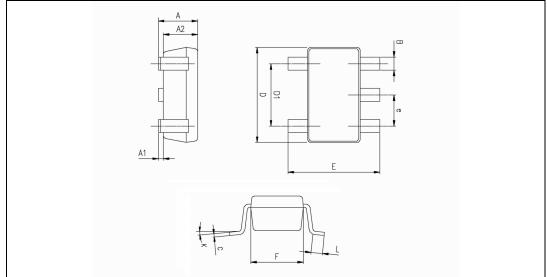


Table 4. SOT23-5 package mechanical data

			Dimen	isions		
Ref.		Millimeters				
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	0.90	1.20	1.45	0.035	0.047	0.057
A1			0.15			0.006
A2	0.90	1.05	1.30	0.035	0.041	0.051
В	0.35	0.40	0.50	0.013	0.015	0.019
С	0.09	0.15	0.20	0.003	0.006	0.008
D	2.80	2.90	3.00	0.110	0.114	0.118
D1		1.90			0.075	
е		0.95			0.037	
Е	2.60	2.80	3.00	0.102	0.110	0.118
F	1.50	1.60	1.75	0.059	0.063	0.069
L	0.10	0.35	0.60	0.004	0.013	0.023
К	0 degrees		10 degrees			



3.2 SO-8 package information



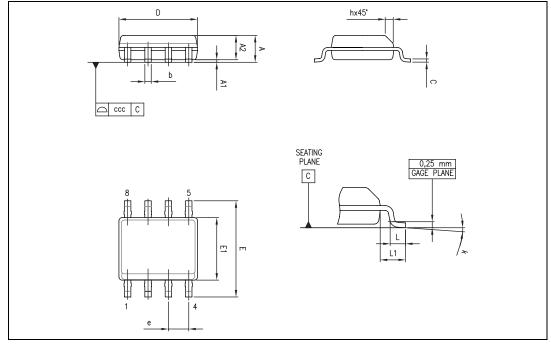


Table 5. SO-8 package mechanical data

	Dimensions							
Ref.	Millimeters				Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
А			1.75			0.069		
A1	0.10		0.25	0.004		0.010		
A2	1.25			0.049				
b	0.28		0.48	0.011		0.019		
С	0.17		0.23	0.007		0.010		
D	4.80	4.90	5.00	0.189	0.193	0.197		
Е	5.80	6.00	6.20	0.228	0.236	0.244		
E1	3.80	3.90	4.00	0.150	0.154	0.157		
е		1.27			0.050			
h	0.25		0.50	0.010		0.020		
L	0.40		1.27	0.016		0.050		
L1		1.04			0.040			
k	0°		8°	1 °		8°		
CCC			0.10			0.004		



3.3 TSSOP8 package information



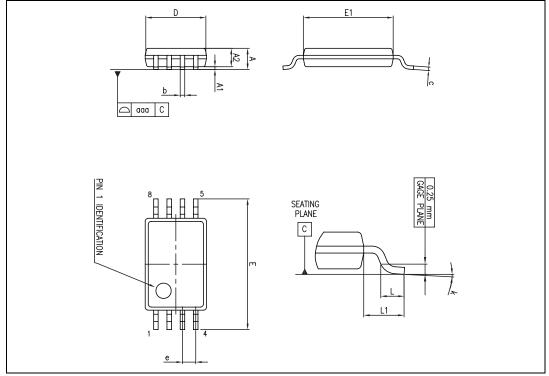


Table 6. TSSOP8 package mechanical data

	Dimensions							
Ref.		Millimeters		Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.		
А			1.20			0.047		
A1	0.05		0.15	0.002		0.006		
A2	0.80	1.00	1.05	0.031	0.039	0.041		
b	0.19		0.30	0.007		0.012		
С	0.09		0.20	0.004		0.008		
D	2.90	3.00	3.10	0.114	0.118	0.122		
Е	6.20	6.40	6.60	0.244	0.252	0.260		
E1	4.30	4.40	4.50	0.169	0.173	0.177		
е		0.65			0.0256			
k	0°		8°	0°		8°		
L	0.45	0.60	0.75	0.018	0.024	0.030		
L1		1.00			0.039			
aaa			0.10			0.004		



3.4 SO-14 package information



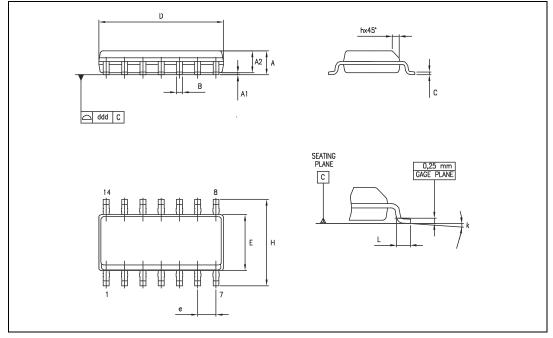


Table 7.SO-14 package mechanical data

	Dimensions									
Ref.		Millimeters			Inches					
Ref.	Min.	Тур.	Max.	Min.	Тур.	Max.				
А	1.35		1.75	0.05		0.068				
A1	0.10		0.25	0.004		0.009				
A2	1.10		1.65	0.04		0.06				
В	0.33		0.51	0.01		0.02				
С	0.19		0.25	0.007		0.009				
D	8.55		8.75	0.33		0.34				
E	3.80		4.0	0.15		0.15				
е		1.27			0.05					
Н	5.80		6.20	0.22		0.24				
h	0.25		0.50	0.009		0.02				
L	0.40		1.27	0.015		0.05				
k			8° (r	nax.)		•				
ddd			0.10			0.004				



3.5 TSSOP14 package information

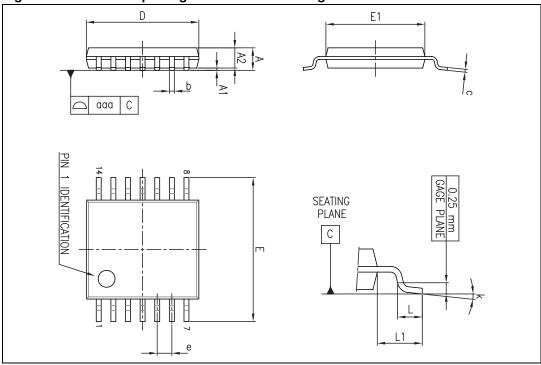


Figure 17. TSSOP14 package mechanical drawing

 Table 8.
 TSSOP14 package mechanical data

	Dimensions								
Ref.		Millimeters			Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.			
А			1.20			0.047			
A1	0.05		0.15	0.002	0.004	0.006			
A2	0.80	1.00	1.05	0.031	0.039	0.041			
b	0.19		0.30	0.007		0.012			
С	0.09		0.20	0.004		0.0089			
D	4.90	5.00	5.10	0.193	0.197	0.201			
Е	6.20	6.40	6.60	0.244	0.252	0.260			
E1	4.30	4.40	4.50	0.169	0.173	0.176			
е		0.65			0.0256				
L	0.45	0.60	0.75	0.018	0.024	0.030			
L1		1.00			0.039				
k	0°		8°	0°		8°			
aaa			0.10			0.004			



DFN8 exposed pad package information 3.6

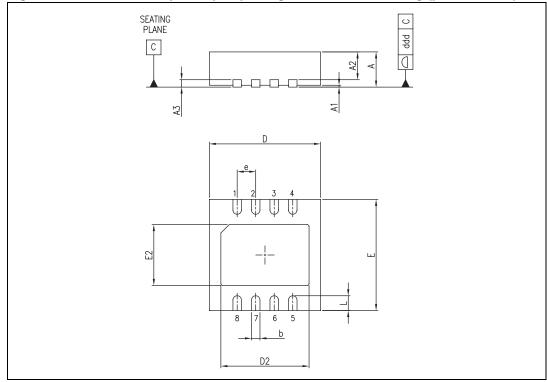
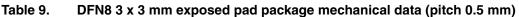


Figure 18.	DFN8 3 x 3 ex	posed pad p	ackage mechanical	drawing (pitch 0.5 mm)

ble 9.	Dinteexe	mm exposed	· · ·						
	Dimensions								
Ref.		Millimeters			Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.			
А	0.80	0.90	1.00	0.031	0.035	0.039			
A1		0.02	0.05		0.0008	0.0019			
A2	0.55	0.65	0.80	0.021	0.025	0.031			
A3		0.20			0.008				
b	0.18	0.25	0.30	0.007	0.010	0.012			
D	2.85	3.00	3.15	0.112	0.118	0.124			
D2	2.20		2.70	0.087		0.106			
E	2.85	3.00	3.15	0.112	0.118	0.124			
E2	1.40		1.75	0.055		0.069			
е		0.50			0.020				
L	0.30	0.40	0.50	0.012	0.016	0.020			
ddd			0.08			0.003			





4 Ordering information

Table 10.Order codes

Order code	Temperature range	Package	Packing	Marking
TS971ID TS971IDT	-40°C, +125°C	SO-8	Tube or Tape & reel	9711
TS971ILT		SOT23-5L	Tape & reel	K120
TS971IYD ⁽¹⁾ TS971IYDT ⁽¹⁾		SO-8 (Automotive grade level)		971IY
TS971IYLT ⁽²⁾		SOT23-5L (Automotive grade level)		K121
TS972ID TS972IDT		SO-8	Tube or Tape & reel	
TS972IPT		TSSOP8 (Thin shrink outline package)	Tape & Reel	9721
TS972IQT		DFN8 (Dual micro lead frame package)		
TS972IYD ⁽¹⁾ TS972IYDT ⁽¹⁾		SO-8 (Automotive grade level)	Tube or Tape & reel	972IY
TS972IYPT ⁽²⁾		TSSOP8 (Automotive grade level)	Tape & reel	972IY
TS974ID TS974IDT		SO-14	Tube or Tape & reel	9741
TS974IPT		TSSOP14 (Thin shrink outline package)	Tape & reel	0771
TS974IYD ⁽¹⁾ TS974IYDT ⁽¹⁾		SO-14 (Automotive grade level)		974IY
TS974IYPT ⁽²⁾		TSSOP14 (Automotive grade level)		974IY

1. Qualified and characterized according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 & Q 002 or equivalent.

2. Qualification and characterization according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 & Q 002 or equivalent are on-going.



5 Revision history

Table 11.	Document revisio	n history
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Date	Revision	Changes	
15-Nov- 2002	1	First release.	
9-May- 2005	2	Modifications on AMR table (explanation of V_{id} and V_i limits)	
31-Aug-2005	3	PPAP references inserted in the datasheet, see Table 1 on page 2.	
9-Dec-2005	4	Thermal resistance junction to case data added in <i>Table 1. on page 2</i> Missing PPAP references inserted in the datasheet, see <i>Table 10:</i> <i>Order codes</i> .	
3-Oct-2007	5	Added R _{thja} and R _{thjc} values for DIP8 and DIP14 packages in <i>Table 1</i> . ESD footnotes updated in <i>Table 1: Absolute maximum ratings AMR</i> . Description section updated on cover page. Markings for automotive grade parts corrected in <i>Table 10: Order codes</i> .	
20-Dec-2007	6	Reformatted package information in <i>Section 3: Package information</i> . Footnotes for automotive grade parts corrected in <i>Table 10: Order codes</i> .	
06-May-2010	7	Updated package information (drawings and data) in <i>Chapter 3</i> . Removed DIP package order codes from <i>Chapter 4: Ordering information</i> .	



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